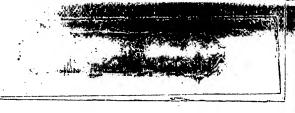
(
	Subclass	SIFICATION	
09/9	Class	ISSNE CLA	

TILE





U.S. UTILITY Patent Application

O.I.P.E. PATENT DATE SCANNED.

	UCATION NO. 09/903070	CONT/PRIOR	CLASS 053	SUBCLASS 449	3721 3721	EXAMINER STOCK	
`₹	Tae-hun S Tee-yeol Kyong-rim Jeong-hoo	Heo · Kano					

Methods of packaging semiconductor wafers by molding a packing bag about a carrying device that contains the semiconductor wafers

		ISSUING C	CLASSIFICATION		
ORIGII	NAL	CROSS REFERENCE(S)			
CLASS	CLASS SUBCLASS		SUBCLASS (ONE SUBCLASS PER BLOCK)		
1			dia mis		
INTERNATION	AL CLASSIFICATION				
		·			
	٠٠,		☐ Continued on Issue Slip Inside File Jacket		

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED		
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.	
☐ The term of this patent		<u> </u>	·	NOTICE OF ALL	OWANCE MAILED	
subsequent to (date) has been disclaimed.	(Assistant	Examiner)	(Date)			
The term of this patent shall not extend beyond the expiration date					i 	
of U.S Patent. No.	•			ISSI	JE FEE	
			Ţ	Amount Due	Date Paid	
	(Primary Examiner)		(Date)			
☐ The terminalmonths of this patent have been disclaimed.				ISSUE BATCH NUMBER		
The patent have been discissified.	(Legal instrume	nts Examiner)	(Date)		_	
WARNING: The information disclosed herein may be rest Possession outside the U.S. Patent & Tradem	tricted. Unauthorized on the control of the control	disclosure may be p	rohibited by the U	nited States Code Title 35	5, Sections 122, 181 and 368	
orm PTO-436A			FILED WITH:	DISK (CBE) [JEICHE DO BOI	

(CRF) FICHE U CD-HONI
(Attached in pocket on right inside flap)